



ATLAS Level-1 Calorimeter Trigger

Joint Meeting @ Stockholm, Jul.2002



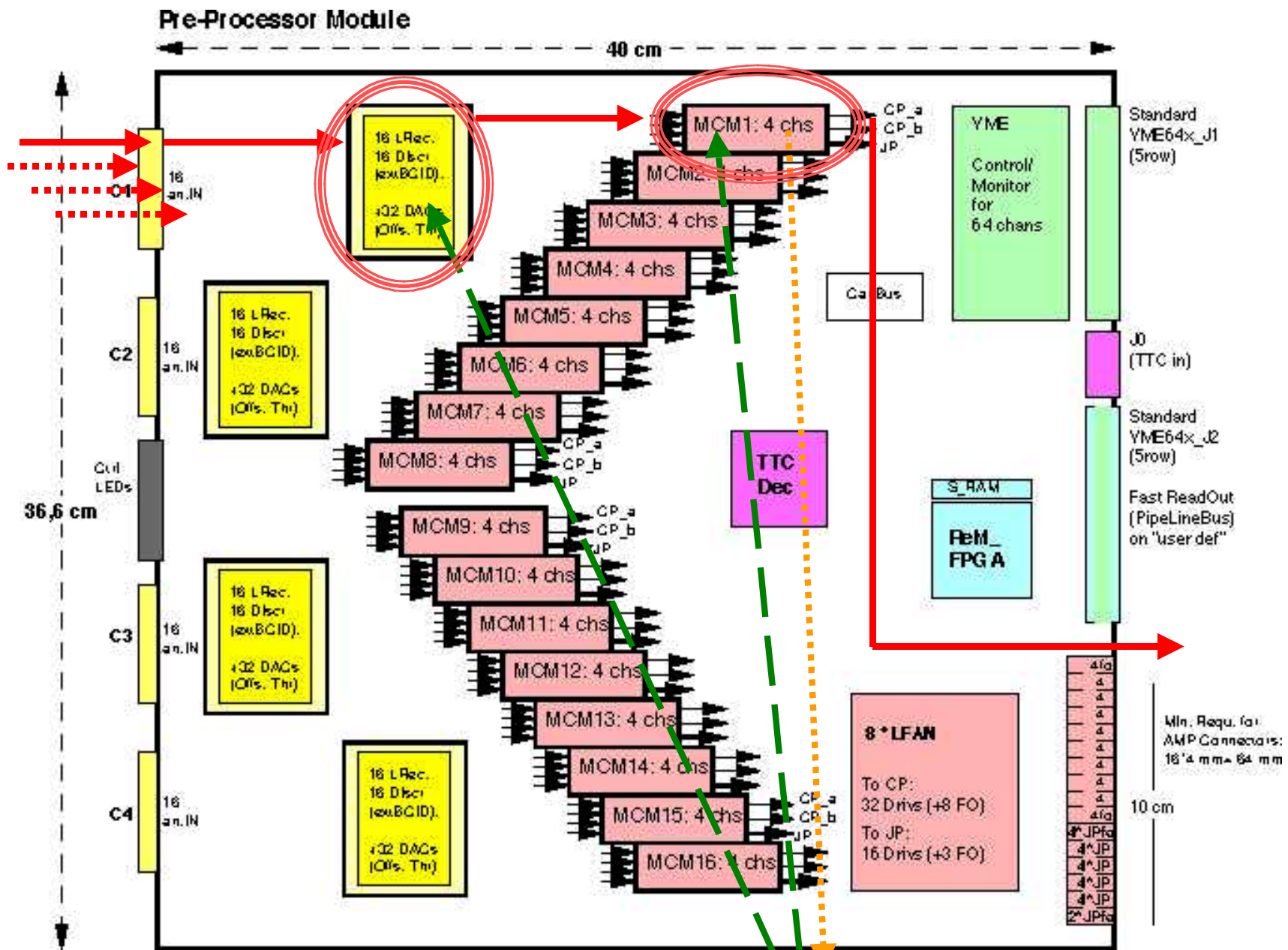
Pre-Processor (System Issues)

- *Status of the PreProcessorModule*
 - sub-components
- *other PreProcessor items*
 - System parts @ Atlas
 - Test Parts
- *Material, Misc...*
- *Planning*

Status of the PPModule

- **Schematics:** *Engineers/Technicians to date busy on test hardware, but*
 - *Commercial parts in libs (SubD37, cPCIs, VMEs)*
 - *AnIn, MCM, TTCrx_dPCB defined in libs*
 - *VME connected*
 - *work on connectivity from front-panel through ... to cPCI*
 - *--- >>> little more since March02 @ HD*

 - *ReM_FPGA on 1.27mm pitch BGA(560 pins)*
 - *LVDS daughterboard to be defined (see later)*
- **PPr “CORE” test:** AnIn, MCM (+ASIC+LVDS), Ser.Readout
 - *priority before PPModule (due to human resources !)*
 - *status given by R.Achenbach and K.Penno*



Paul HANKE, KIP Heidelberg @ Stockholm, 4.July2002

Control / Readout (ser.IF)

- **AnIn daughterboard**
 - *under test*
- **MCM**
 - *under test*
- **PPModule board**
 - *start PCB as soon as resources are free, i.e. now, since "test PCBs" are done.*
- **LVDS serializer implementation** (choice: see later)
 - *60 MHz (1023) die is "footprint" compatible with 40 Mhz (1021) i.e. present MCM layout is OK!*
 - *"dies" are available acc. to distributor !*
- **LVDS daughterboard (cable driver)**
 - *must be started soon; last sub-component for PPModule*
 - *need to prove usability of XCV50e in ongoing tests*

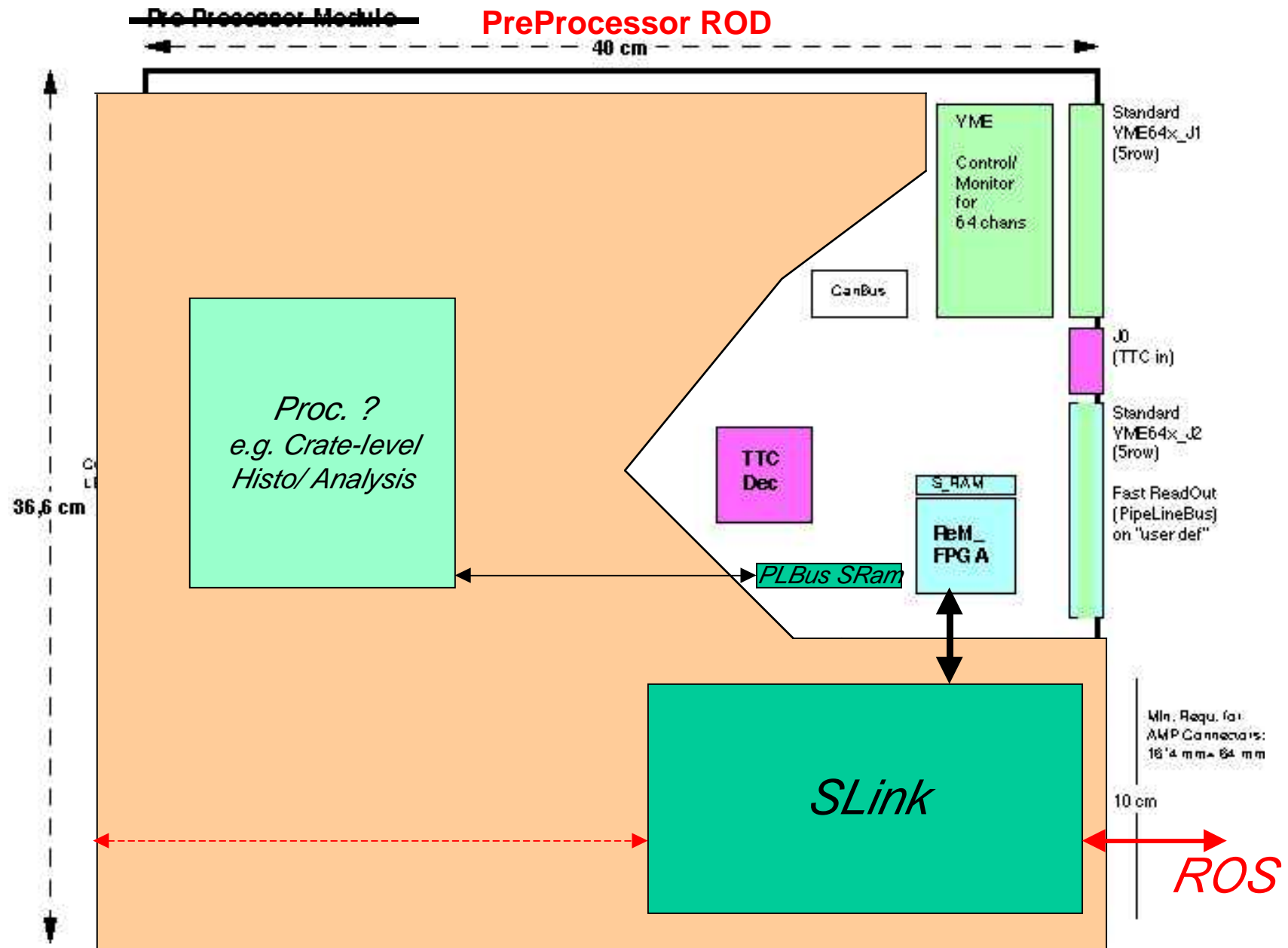
- **ReM_FPGA and PipeLineBus access**

- *ReM_FPGA code development (D.Kaiser) started “from scratch” !
-> Verilog for ReM_ASIC not usable ?!*
- *code has not been implemented on hardware and checked*
- *code size for XCV1000e changed in last development stages (*2 too big ?)*
- *DK promised to carry on part-time: work over code for optimization,
e.g many resources allocated in parallel
where not necessary (* 32 SerIFs)*
- *no feedback yet since May02 ...*

Other Pre-Processor Items

System parts @ Atlas

- **The TCM-adaptor for PPr**
 - motherboard available from RAL
 - no resources yet to take PPr-adaptor further
- **LVDS crate-backplate** (“old”)
 - commercial *solution* from ELMA-Trenew:
8 PPM--slots (3U) for LVDS throughput (B22, B25) with cable-shrouds for AMP-cables
- **The PPr_ROD** as “part of PPM”:
 - final 9u ROD not yet started
 - code for XCV1000E as “*PLBus Master*” (cont. B.Stelzer’s work, who ?)
 - layout -> *see figure*

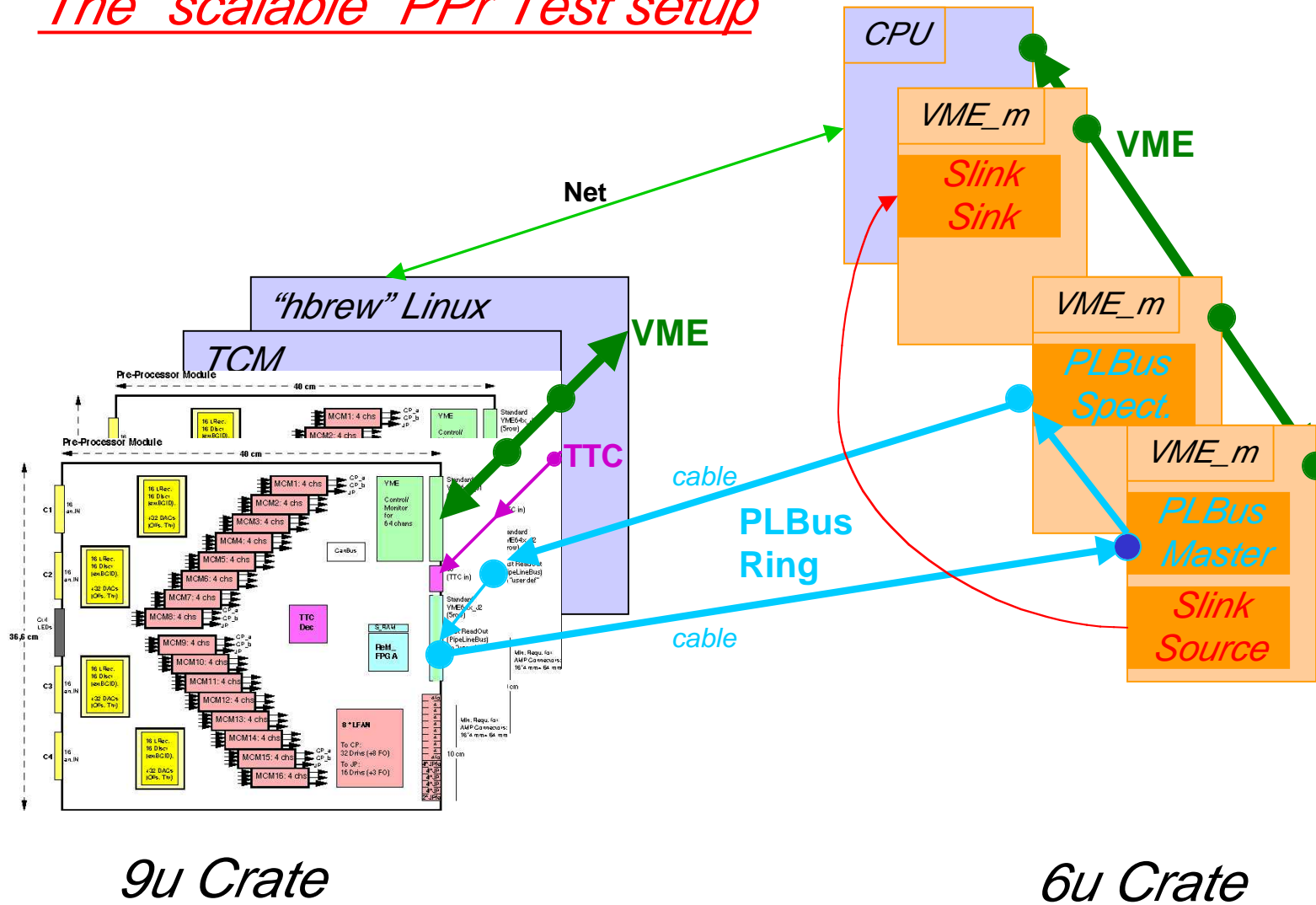


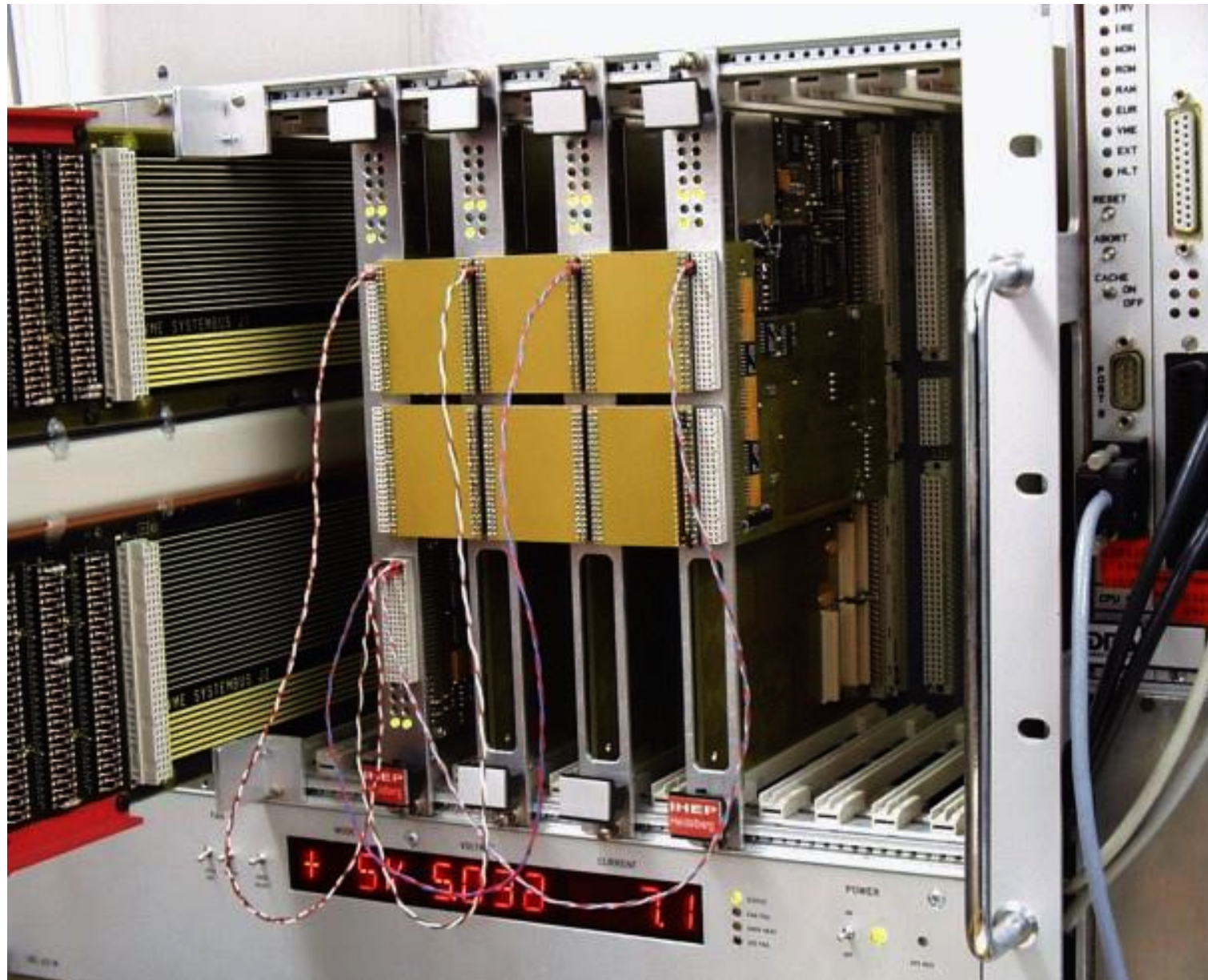
Test Parts

- **Linux “homebrew”** for in-house tests (O.Nix+K.Penno+K.Schmitt)
- **LVDS test PCB** (CMC board for mod.TestVME system):
 - manufactured and Comp.-loaded
 - test 1021 @“40 MHz+epsilon” (LHC clock @ 40.08 MHz)
 - **decide** on version for MCM (1021 @ 40 MHz, 1023 @ 40-60 MHz)
 - ==>> propose 1023 (40-66 MHz) for ATLAS**
 - do “Slice-test” MCMs with 1021 (we have ‘em)

 - >> **bond 1 or 2 MCM with “1023 die-samples”** and test to prove exchangeability
 - test XCV50E as “LFan substitute”
- **pre-ROD (as before on mod.TestVME)**
 - use CMC with XCV300 loaded with B.Stelzer’s “ROD-code”
 - >> “PLBus Master”
 - configure PLBus ring with “short” cable segments
 - > Clock speed of 40 MHz should be possible. -> **see figure**

The "scalable" PPr Test setup





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Material and Misc.

- **Purchase-Summary for the full PPr project:**

- front-panel connectors (SubD37)
- VME connectors for PPM boards (J1, J2 , J0-cPCI)
- cPCI connectors on PPM for LVDS output (B22, B25)
- "Mezzanine" connectors for AnIn, LVDS "LFan"
- ELMA-Trenew: 24 (*8slots)
- ReM_FPGA for PPM (XCV1000E)
- PPrASIC "pre-run"

-->> *ca. 30% of TOTAL Heidelberg CoRe spent*

- much more to get: PPrASICs/ LVDS-1023s/ MCM-conns/ AnIn
PCBs+Comps/ PPM PCBs/ LVDS-drivers PCBs+Comps / VME/ TCMs
/PPRODs (... PH's Excel)

••• "Forget-me-not"s

- *Cabling: (W.Cleland, SteveH, MurroughL -->> docs.)*
- *Tile-receivers: "electrical" specification to be done for US-team+DOE.*
- *Schedules (PRRs ?) -> see TonyG*

Work Planning (with not a soul too many)

Hardware

- **PPModule**

Following MCM-test including LVDS-CMC (with XCV50E),
define “LVDS_Driver” board with fanout, cable driver + precompensation.
--> Schematics+Layout+Manuf. in Sep./Okt.02 (rm)

Finish-up schematics for MainPPM board (e.g LVDS_Driver)
--> PPM Layout+Manuf. in Okt./Nov.02 (ps)

- **TCM: PPr_Adaptor**

Finish-up schematics; Layout+Manuf. in Aug./Sep.02 (eu)

- **PPROD (9u)** after PPM in late02/Jan.03

Work Planning (cont.)

Tests and Software

- *MCM (incl. ASIC) tests*

- > ongoing (and maybe finished) till KIP-removal in *Sep.02*.

- > C-Software to be extended continually from KPenno's work, to run "wafer-probe" test

- *PPr subsystem tests* (PPM + VME config. as outlined) in *autumn02*

- > include *TTCvi,vx* in test software... using *TCM*

- > extend VME test software to PPM module level ...

- > *ReM_FPGA* code...?.. (compatible with existing pre-ROD ?)

eop

